Memorandum

PARAMAX A Unisys Company

DATE:

July 13, 1993

PPM-93-070

TO:

B. Fafaul/311.1

FROM:

K. Sahu/300.1 +5

SUBJECT:

Radiation Report on SWAS/MUE

Part No. OMH3075SA

cc: T. Miccolis/300.1 A. Sharma/311.0

Library/311

A radiation evaluation was performed on OMH3075S (Hall Effect Sensor (Latch)) to determine the total dose tolerance of these parts. The total dose testing was performed using a cobalt-60 gamma ray source. During the radiation testing, eight parts were irradiated under bias (see Figure 1 for bias configuration), and two parts were used as control samples. The total dose radiation levels were 5, 10, 20, 40, and 60 krads*. The dose rate was between 0.07 and 1.00 krads/hour, depending on the total dose level (see Table II for radiation schedule). After 60 krads, parts were annealed at 25°C for 168 hours, after which the parts were irradiated to a total dose of 100 krads (cumulative). After the 100-krad irradiation, the parts were annealed at 100°C for 168 hours. After each radiation exposure and annealing treatment, parts were electrically tested according to the test conditions and the specification limits listed in Table III.

All parts passed initial electrical measurements. All eight irradiated parts passed all electrical tests throughout all irradiation and annealing steps. No significant sensitivity to radiation was observed in any test parameters.

Table III provides a summary of the mean and standard deviation values for each parameter after different irradiation exposures and annealing steps.

Any further details about this evaluation can be obtained upon request. If you have any questions, please call me at (301) 731-8954.

^{*}The term rads, as used in this document, means rads(silicon). All radiation levels cited are cumulative.

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TABLE I. Part Information

Generic Part Number: OMH30758

Part Number: OMH3075S*

Control Number: 7343

Charge Number: C33580

Manufacturer: Optek

Lot Date Code: 9217

Quantity Tested: 5

Serial Numbers of

Radiation Samples: 254, 275, 293, 709, 722, 750, 771, 792

Serial Numbers of

Control Samples: 213, 223

Part Function: Hall Effect Sensor (Latch)

Part Technology: CMOS

Package Style: 3-pin Ceramic

Test Equipment: Sentry S-50

Test Engineer: T. Mondy

^{*}No radiation tolerance/hardness was guaranteed by the manufacturer for this part.

TABLE II. Radiation Schedule for OMH3075S

EVENTS	DATE
1) INITIAL ELECTRICAL MEASUREMENTS	05/27/93
2) 5 KRAD IRRADIATION (0.24 KRADS/HOUR) POST-5 KRAD ELECTRICAL MEASUREMENT	06/03/93 06/04/93
3) 10 KRAD IRRADIATION (0.07 KRADS/HOUR) POST-10 KRAD ELECTRICAL MEASUREMENT	06/04/93 06/07/93
4) 20 KRAD IRRADIATION (0.50 KRADS/HOUR)	06/07/93
POST-20 KRAD ELECTRICAL MEASUREMENT	06/08/93
5) 40 KRAD IRRADIATION (1.00 KRADS/HOUR)	06/08/93
POST-40 KRAD ELECTRICAL MEASUREMENT	06/09/93
6) 60 KRAD IRRADIATION (1.00 KRADS/HOUR)	06/09/93
POST-60 KRAD ELECTRICAL MEASUREMENT	06/10/93
7) 168 HOUR ANNEALING @25°C	06/10/93
POST-168 HOUR ANNEAL ELECTRICAL MEASUREMENT	06/18/93
8) 100 KRAD IRRADIATION (0.56 KRADS/HOUR)	06/18/93
POST-100 KRAD ELECTRICAL MEASUREMENT	06/22/93
9) 168 HOUR ANNEALING @100°C* POST-168 HOUR ANNEAL ELECTRICAL MEASUREMENT	06/22/93 07/07/93

PARTS WERE IRRADIATED AND ANNEALED UNDER BIAS; SEE FIGURE 1.

^{*}High temperature annealing is performed to accelerate long term time dependent effects (TDE), namely, the "rebound" effect due to the growth of interface states after the radiation exposure. For more information on the need to perform this test, refer to MIL-STD-883D, Method 1019, Para. 3.10.1.

Table III. Electrical Characteristics of OMH30758

TEST	CONDITIONS	LIMI	LIMITS	
. ,—.		MIN	MAX	
ICC	VCC = 24V, B < 250G	0	7.0	mA
BOP1	VCC = 4.5V	50	250	G
вор2	VCC = 24V	50	250	Ġ
BRP1	VCC = 4.5V	-250	-50	G
BRP2	VCC = 24V	-250	-50	G
BHYS1	VCC = 4.5V, BHYS = BOP - BRP	100	500	G
BHYS2	VCC = 24V, BHYS = BOP - BRP	100	500	G
VSAT	VCC = 4.5V, B > 250G, IOUT = 20mA	0	400	mV
IOH	VCC = 24V, VOUT = 24V, B < 250G	0	1.0	μA

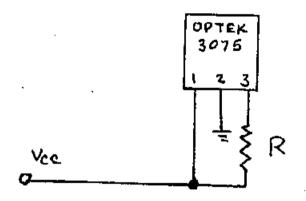
Table IV: Summary of Electrical Measurements After Total Dose Exposures and Annealing for OMH3075S 1/

Anneal	Ers	\$100°C	5 Ĝ	2:	34	36	6£	4.8	36	37	21	<u></u>
	158	3.10	mean	6 30	166	72.7	(2) (1)	9	7.67	31.1	6.9	
IDE	160	160 kr ads	ಗ ಬ	, 11	27	53	52	9	45	47	13	ŀ
			mean	₹.21	181	161	97	-148	336	348	176	4
31	Hrs	@25°C	şģ	. 1 1	27	53	57	54	43	UST FC∰	25	6
Annea	168	@ 5;	mean	67.7	0.1	180	100	2)	919	3.28	0.91	100
	ţ.		iD D	, 11	26	30	95	09	50	50	7.6	٠-
(gp)	99		mean	\$ 3	 86 ∏	₹ 6.	7	143	330	ě	99T	0.0
(Krads			s O	.11	3.0	3.4	4 9	58	6.5	50	7.6	_
(ICI)	4.0		Mean	4.27	179	183	-140	\$ 1	10 (3 (7)	. 4 .	165	LU U
ure	_		Вđ	.1 1	27	23	43	53	44	44	25	_
Exposure	20		mean	7 . 7	175	28 1	¥133	0#1-	3.1	327	891	
Dose	_		sd	1.	21	25	43	53	4.7	4.5	3.0	0
Total D	0.1		mean	2) 7 8	2 1	9 6	Z£1-	56 T =	306	318	LOI	. C
CL			sd	, 11	32	37	48	28	58	5.3	40	Œ
į	<u>μ</u> 1		mean	1 P . D	174	29 21	2£1-	-135	31.2	322	59	
ial			sd	. 11	31	35	40	48	7.5	3.8	4.7	~
Initial	□		mean	4.44	164	31T	121	124	289	652	149	0.0
	Spec.	Lim./2	Max	7.0	250	250	09-	-20	500	005	400	1.6
	Sp.	Sp	min	0	50	5.0	G -250	-253	100	100	0	0
				mА	G	ט	O	G	ט	O	A T	Δ.
			Parameters	ICC,	EOP1,	EOP2,	BRP1,	BRP2.	BHYSI,	BHYS2,	VSAT,	TOH.

1/ The mean and standard deviation values were calculated over the eight parts irradiated in this testing. The control samples remained constant throughout the testing and are not included in this table.

2/These are manufacturer's non-irradiated data sheet specification limits. No post-irradiation limits were provided by the manufacturer at the time the lests were performed.

Figure 1. Radiation Bias Circuit for OMB30758 1/, 2/



 $1/ \text{Vcc} = 24.0 \text{ V } \pm 0.5 \text{ V}$

 $2/R = 5.1 K\Pi, \frac{1}{4}W$